AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the subject application.

1. – 21. (Canceled)

22. (Original) A method for manufacturing a Z-directed component for insertion into a mounting hole in a printed circuit board, comprising:

extruding a substrate material through an extrusion die having a chamber defining the shape of the extruded substrate material including forming at least one channel through the substrate material with a corresponding projection in the extrusion die;

dividing the extruded substrate material into a plurality of layers of the Z-directed component according to the thickness of each layer;

applying a conductive material to a surface of at least one of the layers; and

combining a stack of the layers to form the Z-directed component.

23. (Original) The method of claim 22, further comprising extruding the substrate material in longitudinal segments and combining the longitudinal segments according to the shape of the Z-directed component, wherein the projection is positioned along an edge of the chamber and forms a partial channel in each extruded segment, and a complete channel is formed in an interior portion of the substrate material when the segments are combined.

24. (Original) The method of claim 22, wherein the projection is spaced inward from an edge of the chamber and connected to the edge of the chamber by a support member, and a gap formed in the extruded substrate material by the support member is eliminated by rejoining corresponding portions of the substrate material.

25. (Original) The method of claim 24, wherein the corresponding portions of the substrate material are rejoined after extrusion is complete.

26. (Original) The method of claim 24, wherein the corresponding portions of the substrate material are rejoined in a continuous process downstream from extrusion.

27. (New) The method of claim 26, further comprising supporting the extruded longitudinal segments with a moving member from a downstream end of the substrate material as it advances.

28. (New) The method of claim 22, wherein combining the stack of the layers to form the Z-directed component includes heating and compressing the stacked layers to form an aggregate part.